



AMENDMENT UNDER 37 C.F.R. § 1.116
EXAMINING GROUP 2822

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By

Alfred I-Tsung Pan

Date: March 18, 2003

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): **Alfred I-Tsung Pan**

Group Art Unit: **2822**

Serial No.: **09/655,197**

Examiner: **Soward, Ida**

Filed: **September 5, 2000**

Confirmation No.: **7747**

Title: **Monolithic Common Carrier**

Atty Docket: **10992304-1**

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RESPONSE PURSUANT TO 37 C.F.R. 1.116

Hon. Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action mailed **November 20, 2002**, please consider the following remarks.

IN THE CLAIMS:

1. (Twice Amended) A common carrier, comprising:

a carrier substrate having an upper surface; and

a plurality of integrated chips adhered on the upper surface and aligned with each other and the substrate with a lithographic alignment tolerance.

REMARKS

Applicant respectfully requests reconsideration of the application in view of the following remarks.

Amendments

Claim 1 is amended to more clearly define the subject matter of the claimed invention. Specifically, Claim 1 is amended to indicate that the plurality of integrated chips

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